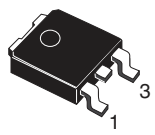
STD150NH02L-1
STD150NH02L

N-channel 24V - 0.003Ω - 150A - ClipPAK™ - IPAK STripFET™ III Power MOSFET

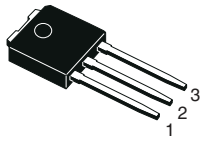
General features

Type	V_{DSSS}	$R_{DS(on)}$	I_D
STD150NH02L	24V	<0.0035Ω	150A
STD150NH02L-1	24V	<0.0035Ω	150A

- $R_{DS(on)}$ * Qg industry's benchmark
- Conduction losses reduced
- Switching losses reduced
- Low threshold device



ClipPAK™

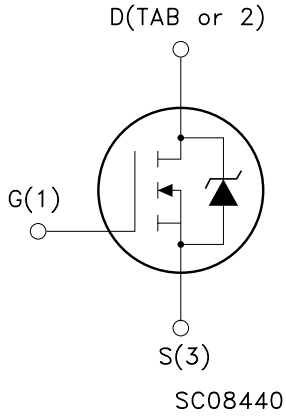


IPAK

Description

The STD150NH02L utilizes the latest advanced design rules of ST's proprietary STripFET™ technology. This novel 0.6µ process utilizes also unique metallization techniques that couple to a "bondless" assembly technique result in outstanding performance with standard DPAK outline. It is therefore ideal in high performance DC-DC converter applications where efficiency it to be achieved at very high out currents.

Internal schematic diagram



Applications

- Switching application

Order codes

Part number	Marking	Package	Packaging
STD150NH02LT4	D150NH02L	ClipPAK™	Tape & reel
STD150NH02L-1	D150NH02L	IPAK	Tube

Contents

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{spike} (1)	Drain-source voltage rating	30	V
V_{DS}	Drain-source voltage (V_{GS} = 0)	24	V
V_{DGR}	Drain-gate voltage (R_{GS} = 20KΩ)	24	V
V_{GS}	Drain-source voltage	± 20	V
I_D	Drain current (continuous) at T_C = 25°C	150	A
I_D	Drain current (continuous) at T_C=100°C	107	A
I_{DM} (2)	Drain current (pulsed)	600	A
P_{TOT}	Total dissipation at T_C = 25°C	125	W
	Derating factor	0.83	W/°C
E_{AS} (3)	Single pulse avalanche energy	500	mJ
T_{stg}	Storage temperature	-55 to 175	°C
T_J	Max. operating junction temperature		

1. Garanted when external Rg = 4.7 Ω and $t_f < t_{fmax}$.
2. Pulse width limited by safe operating area
3. Starting T_J = 25 °C, I_D = 75A, V_{DD} = 10V

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case Max	1.2	°C/W
R_{thJA}	Thermal resistance junction-ambient Max	100	°C/W
T_l	Maximum lead temperature for soldering purpose	275	°C

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Table 3. On(1) /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 25mA, V_{GS} = 0	24			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 20V V_{DS} = 20V, T_C = 125°C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ±20V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250µA	1	1.8		V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS} = 10V, I_D = 75A V_{GS} = 5V, I_D = 37.5A		0.003 0.004	0.0035 0.0065	Ω Ω

1. Pulsed: Pulse duration = 300 µs, duty cycle 1.5%

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward transconductance	V_{DS} = 10 V, I_D = 75A		60		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 15V, f = 1 MHz, V_{GS} = 0		4450 1126 141		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 16V, I_D = 150A V_{GS} = 10V		69 13 9	93	nC nC nC
Q_{oss}(2)	Output charge	V_{DS} = 16V, V_{GS} = 0V		27		nC
Q_{gls}(3)	Third-quadrant gate charge	V_{DS} < 0V, V_{GS} = 10V		64		nC
R_G	Gate input resistance	f = 1MHz gate DC Bias = 0 Test signal level = 20mV Open drain		1.6		Ω

1. Pulsed: pulse duration=300µs, duty cycle 1.5%
2. $Q_{oss} = C_{oss}{}^{*}\Delta V_{in}$, $C_{oss} = C_{gd} + C_{ds}$. See Appendix A
3. Gate charge for synchronous operation

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 10V, I_D = 75A, R_G = 4.7Ω, V_{GS} = 10V *Figure 13 on page 8*		14 224 69 40	 54	ns ns ns ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain current				150	A
I_{SDM}	Source-drain current (pulsed)				600	A
V_{SD} (1)	Forward on voltage	I_{SD} = 75A, V_{GS} = 0			1.15	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 150A, di/dt = 100A/µs, V_{DD} = 15V, T_J = 150°C *Figure 15 on page 8*		47 58 2.5		ns µC A

1. Pulsed: pulse duration=300µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

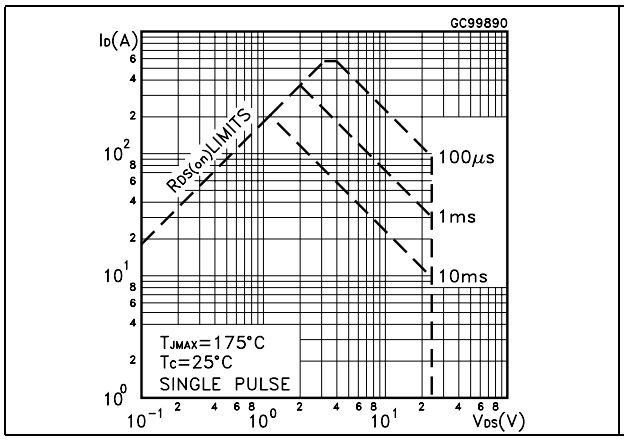


Figure 2. Thermal impedance

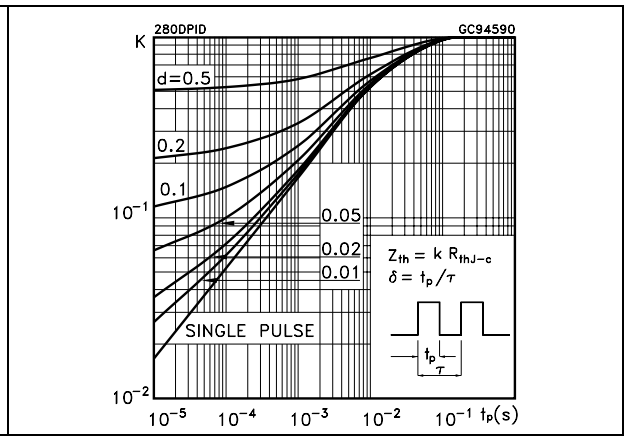


Figure 3. Output characterisics

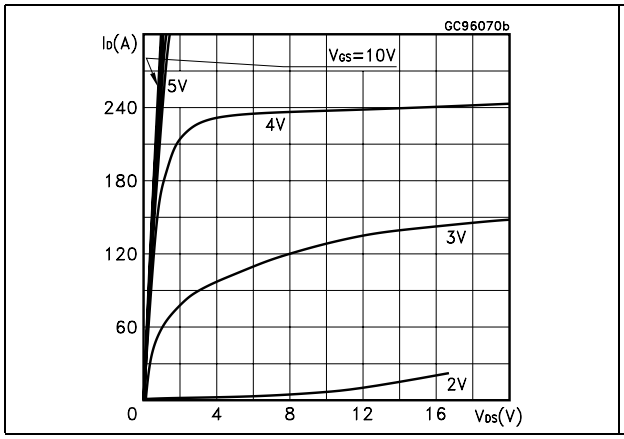


Figure 4. Transfer characteristics

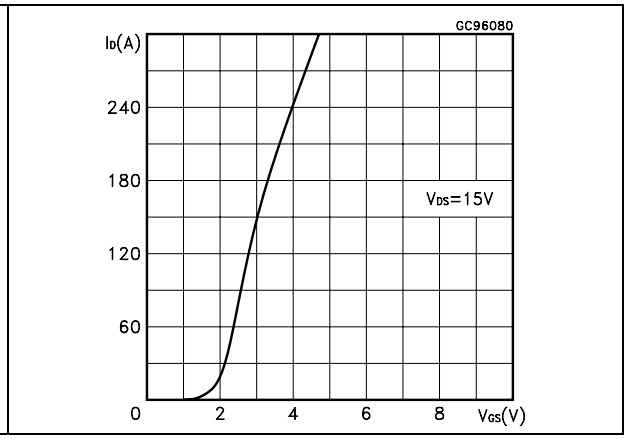


Figure 5. Transconductance

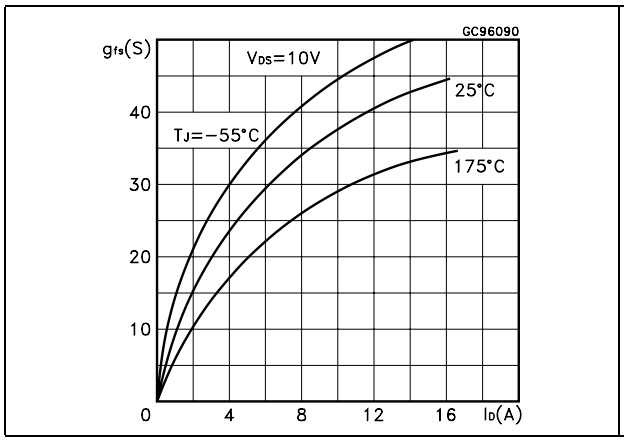


Figure 6. Static drain-source on resistance

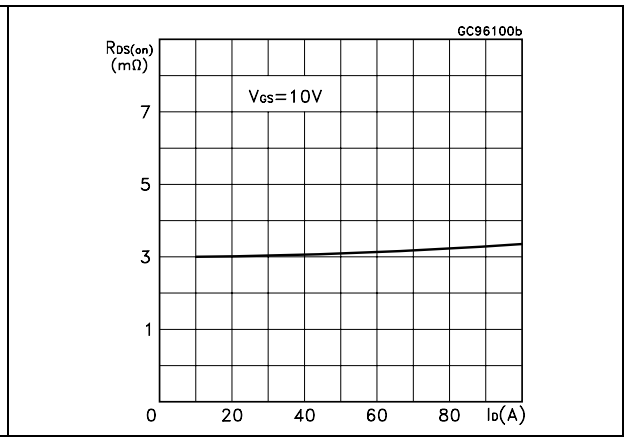


Figure 7. Gate charge vs gate-source voltage

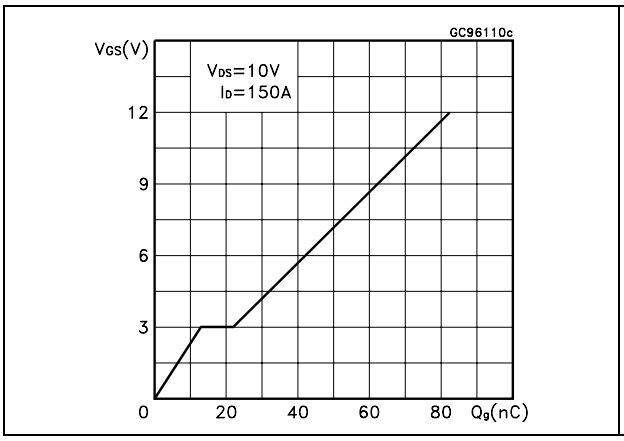


Figure 8. Capacitance variations

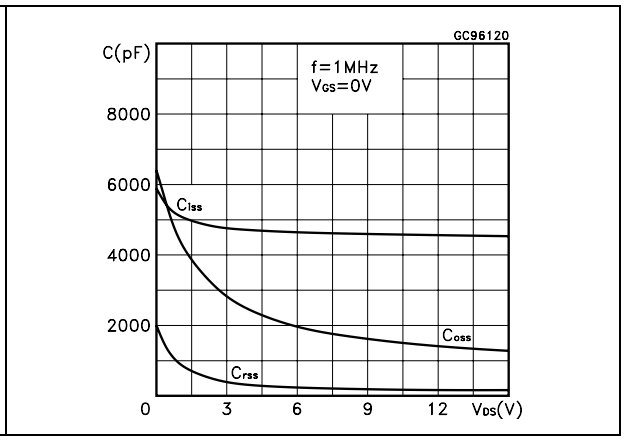


Figure 9. Normalized gate threshold voltage vs temperature

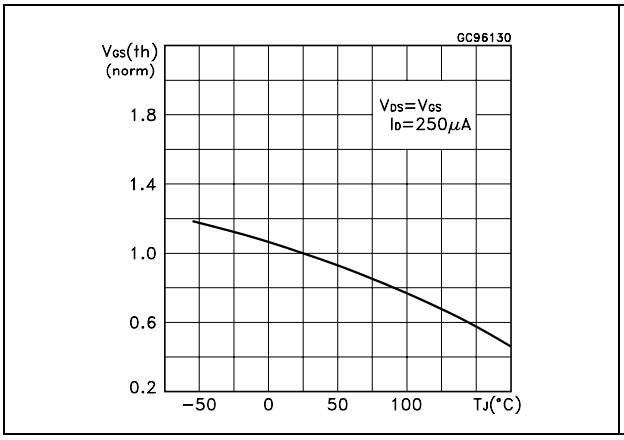


Figure 10. Normalized on resistance vs temperature

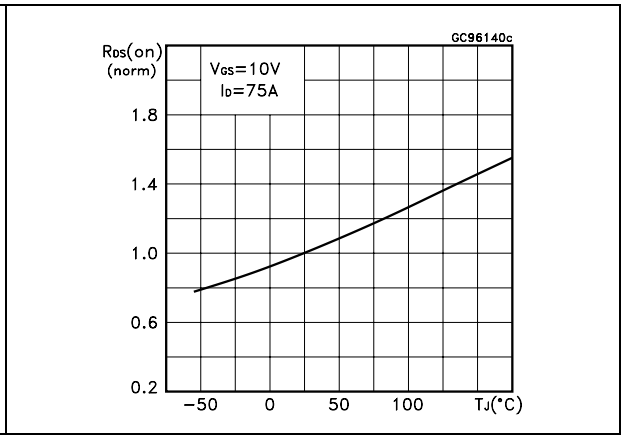


Figure 11. Source-drain diode forward characteristics

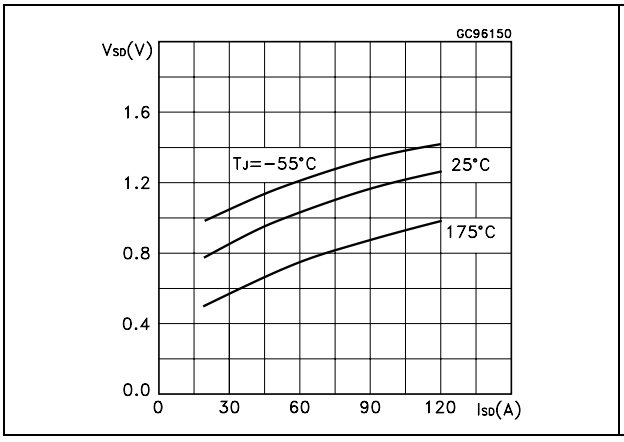
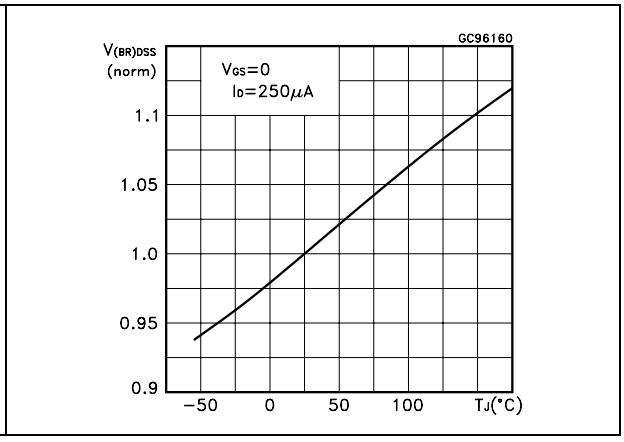


Figure 12. Normalized breakdown voltage vs temperature



3 Test circuit

Figure 13. Switching times test circuit for resistive load

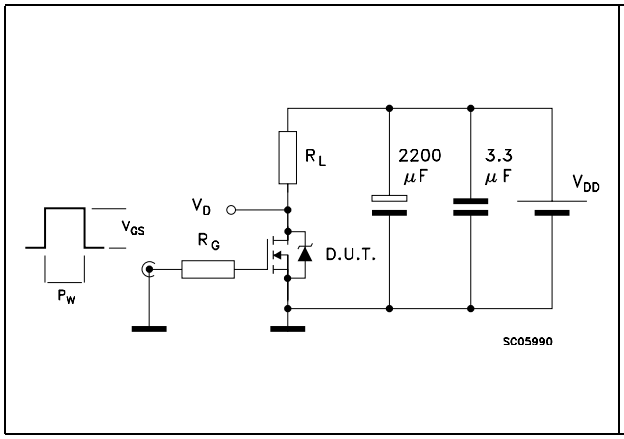


Figure 14. Gate charge test circuit

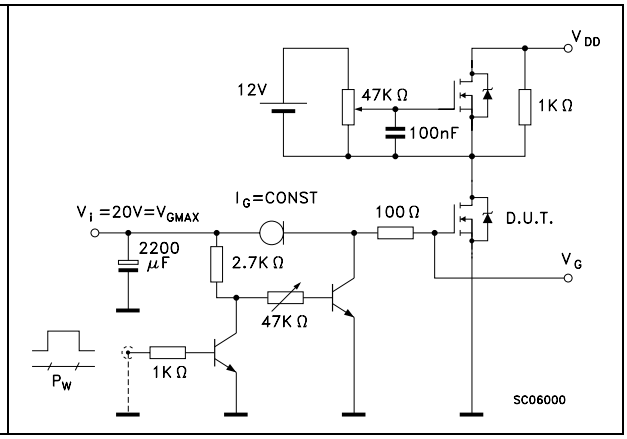


Figure 15. Test circuit for inductive load switching and diode recovery times

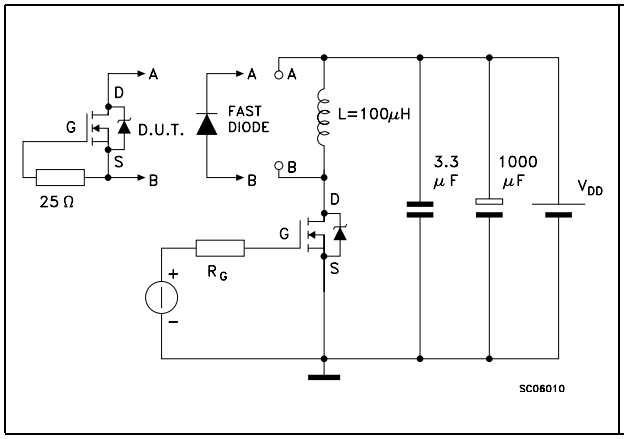


Figure 16. Unclamped Inductive load test circuit

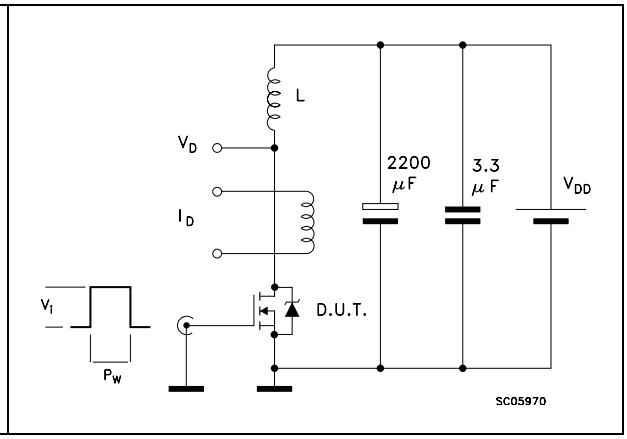
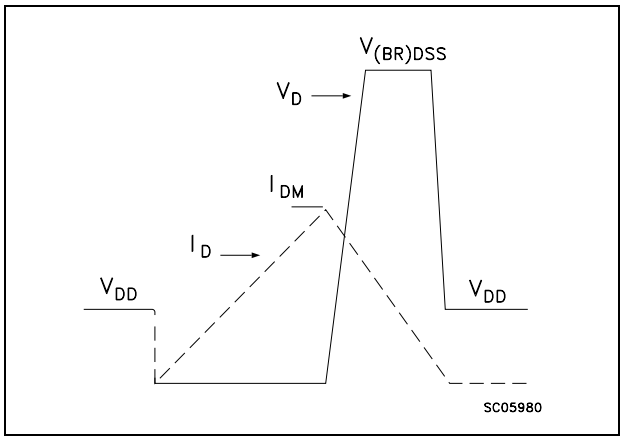


Figure 17. Unclamped inductive waveform

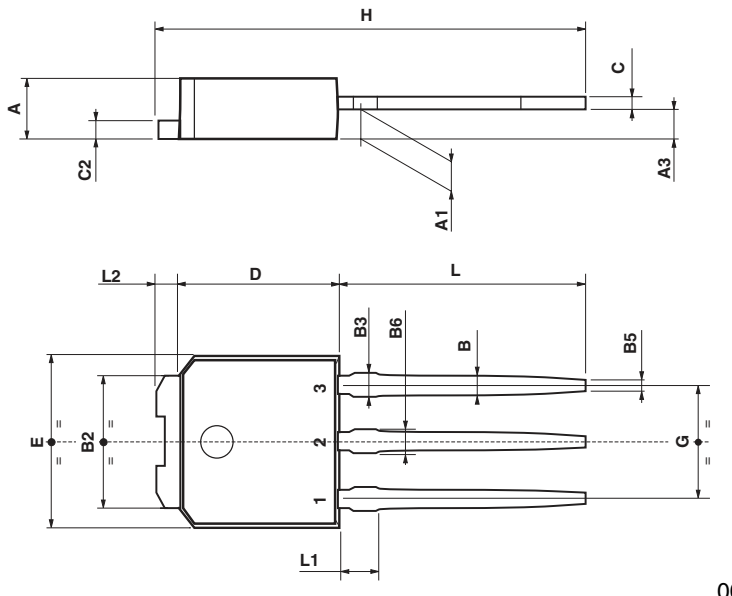


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-251 (IPAK) MECHANICAL DATA

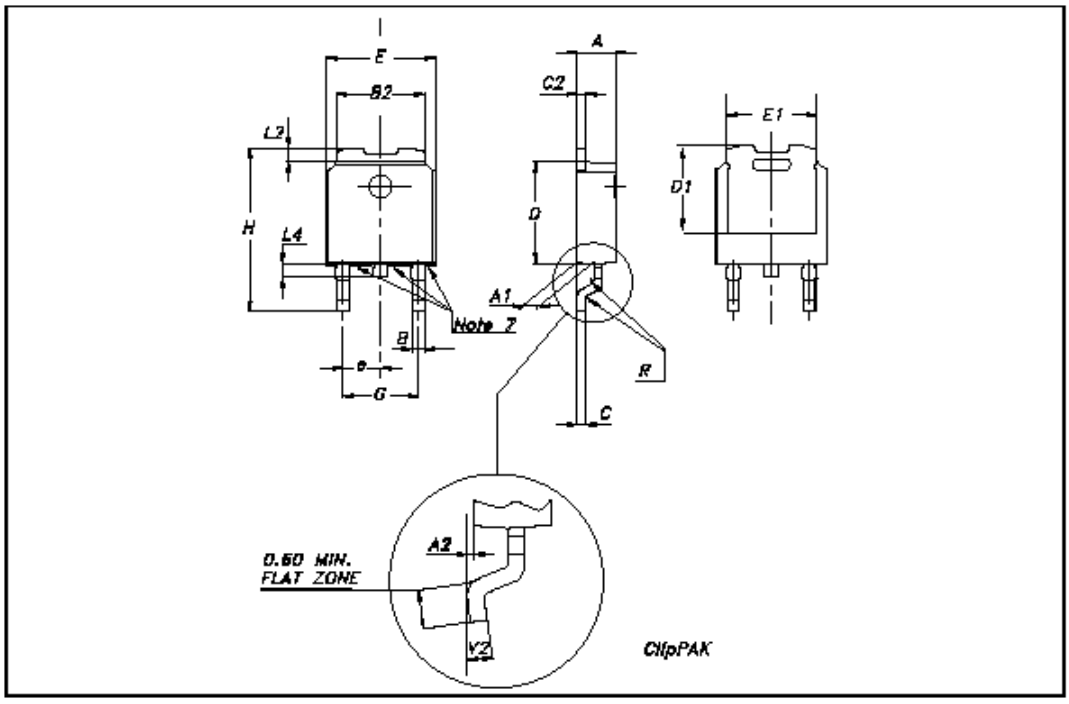
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.031
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.012	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039



0068771-E

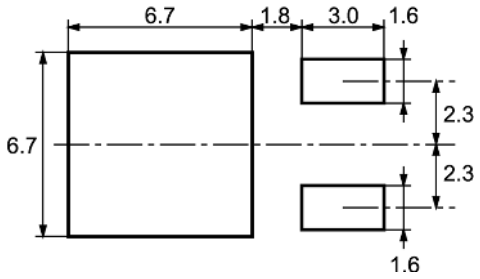
ClipPAK™

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
C	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
D1		5.10			0.200	
E	6.40		6.60	0.252		0.260
E1		5.20			0.204	
e		2.28			0.089	
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°



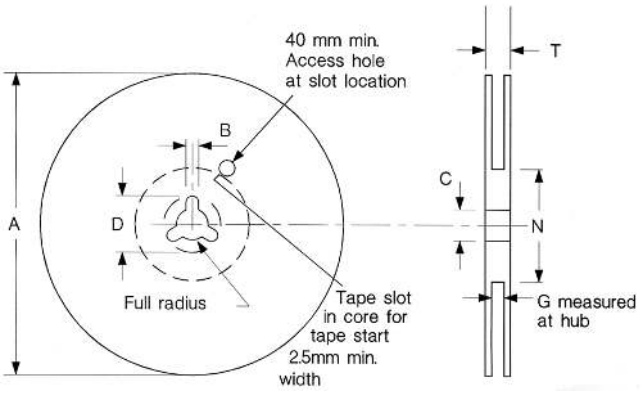
5 Packaging mechanical data

DPAK FOOTPRINT



All dimensions are in millimeters

TAPE AND REEL SHIPMENT



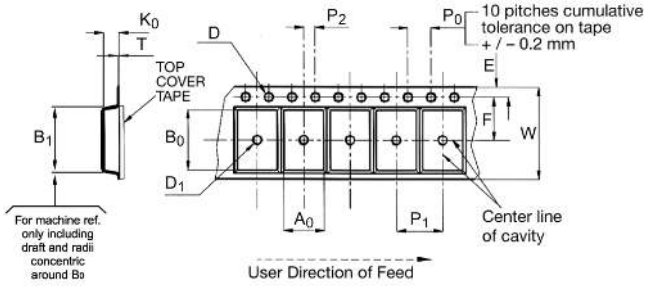
REEL MECHANICAL DATA

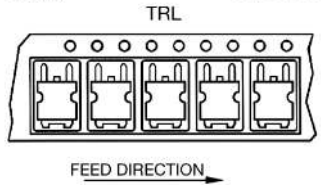
DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A		330		12.992
B	1.5		0.059	
C	12.8	13.2	0.504	0.520
D	20.2		0.795	
G	16.4	18.4	0.645	0.724
N	50		1.968	
T		22.4		0.881

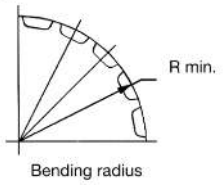
BASE QTY	BULK QTY
2500	2500

TAPE MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	6.8	7	0.267	0.275
B0	10.4	10.6	0.409	0.417
B1		12.1		0.476
D	1.5	1.6	0.059	0.063
D1	1.5		0.059	
E	1.65	1.85	0.065	0.073
F	7.4	7.6	0.291	0.299
K0	2.55	2.75	0.100	0.108
P0	3.9	4.1	0.153	0.161
P1	7.9	8.1	0.311	0.319
P2	1.9	2.1	0.075	0.082
R	40		1.574	
W	15.7	16.3	0.618	0.641

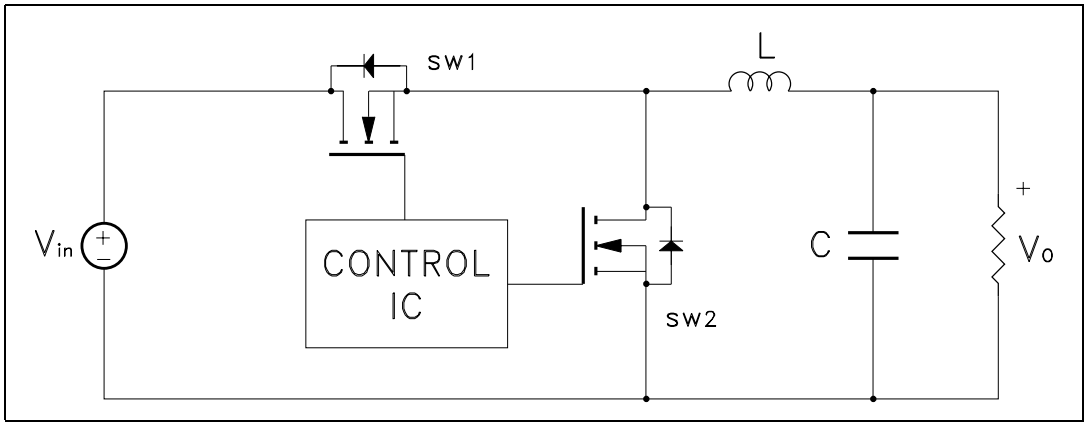






Appendix A Buck converter - power losses estimation

Figure 18. Buck converter: power losses estimation



The power losses associated with the FETs in a synchronous buck converter can be estimated using the equations shown in the table below. The formulas give a good approximation, for the sake of performance comparison, of how different pairs of devices affect the converter efficiency. However a very important parameter, the working temperature, is not considered. The real device behavior is really dependent on how the heat generated inside the devices is removed to allow for a safer working junction temperature.

- The low side (SW2) device requires:
- Very low $R_{DS(on)}$ to reduce conduction losses
- Small Qgls to reduce the gate charge losses
- Small Coss to reduce losses due to output capacitance
- Small Qrr to reduce losses on SW1 during its turn-on
- The Cgd/Cgs ratio lower than Vth/Vgg ratio especially with low drain to source
- voltage to avoid the cross conduction phenomenon;
- The high side (SW1) device requires:
- Small Rg and Ls to allow higher gate current peak and to limit the voltage feedback on the gate
- Small Qg to have a faster commutation and to reduce gate charge losses
- Low $R_{DS(on)}$ to reduce the conduction losses.

Table 7. Power losses calculation

		High side switching (SW1)	Low side switch (SW2)
Pconduction		$R_{DS(on)SW1} * I_L^2 * \delta$	$R_{DS(on)SW2} * I_L^2 * (1-\delta)$
Pswitching		$V_{in} * (Q_{gsth(SW1)} + Q_{gd(SW1)}) * f * \frac{I_L}{I_g}$	Zero Voltage Switching
Pdiode	Recovery (1)	Not applicable	$V_{in} * Q_{rr(SW2)} * f$
	Conduction	Not applicable	$V_{f(SW2)} * I_L * t_{deadtime} * f$
Pgate(Q_G)		$Q_{g(SW1)} * V_{gg} * f$	$Q_{gls(SW2)} * V_{gg} * f$
P_{Qoss}		$\frac{V_{in} * Q_{oss(SW1)} * f}{2}$	$\frac{V_{in} * Q_{oss(SW2)} * f}{2}$

1. Dissipated by SW1 during turn-on

Table 8. Paramiters meaning

Parameter	Meaning
d	Duty-cycle
Q_{gsth}	Post threshold gate charge
Q_{gls}	Third quadrant gate charge
Pconduction	On state losses
Pswitching	On-off transition losses
Pdiode	Conduction and reverse recovery diode losses
Pgate	Gate drive losses
P_{Qoss}	Output capacitance losses

6 Revision history

Table 9. Revision history

Date	Revision	Changes
09-Sep-2004	6	Preliminary data
21-Jun-2005	7	Complete version with curves
28-Jul-2006	8	The document has been reformatted
20-Dec-2006	9	Typo mistake on *Table 3.*

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